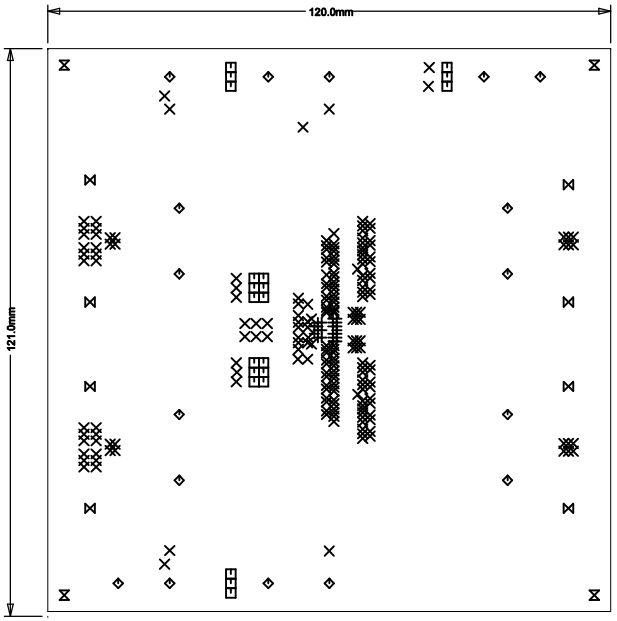
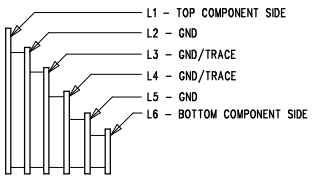
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
–	3	PRODUCTION	SL	04-05-21



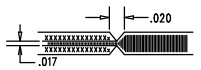
TOP COMPONENT SIDE SHOWN

LAYER CONSTRUCTION



NOTES: UNLESS OTHERWISE SPECIFIED

1. ARTWORK P/N DC3051A REV 3.
2. FAB PER IPC-A-600
3. PCB SHALL MEET RoHS COMPLIANCE.
4. MATERIAL:
   A. LAMINATE: EPOXY FIBERGLASS, NEMA GRADE FR-4 FLAMMABILITY RATING: 94 V-2 MINIMUM .
   B. THICKNESS: 1.6 +/- 0.1 mm
   C. CLAD: 2 OZ. (50um) EXTERNAL LAYERS. 1 OZ. (50um) COPPER ON ALL INTERNAL LAYERS.
5. FINISH:
   A. COATING: SOLDERMASK OVER BARE COPPER, COLOR, GREEN LPI.
   B. PLATING: GOLD IMMERSION BOTH SIDES.
   C. SILKSCREEN: BOTH COMPONENT SIDES WITH WHITE NON-CONDUCTIVE INK.
6. TOLERANCES:
   A. WARPAGE: (0.075mm) MAX. ALONG THE LONGEST DIAG. AS PER IPC-TM650 METHOD 2.4.22.
   B. ETCHING: +0.03mm, -0.3mm OF MASTER PATTERN.
   C. REGISTRATION: 0.075mm MAX.
   D. MASK THICKNESS: 0.025mm MIN., 0.075mm MAX.
   E. HOLE PLATING: 22um +/- 3um.
7. SIZE:
   A. CUT TO DIMENSIONS AND TOLERANCES SHOWN. 0.00 ARE PRIMARY DATUMS.
8. HOLE DIAMETERS ARE POST-PLATED SIZES.
9. DEBURR AND BREAK ALL SHARP EDGES.
10. DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.
11. PLUG ALL VIA'S WITH CONDUCTIVE COPPER PASTE AND PLATE OVER. PLANARIZE FINAL SURFACE.
12. DESIGN HAS SOLDERMASK SIZE DEFINED ON U1. U1 SODERMASK SIZE IS 0.040mm AND PAD SIZE IS 0.050mm. DO NOT CHANGE PAD SIZE OR SOLDERMASK SIZE.
13. SCORING FOR PANELIZED PCB:



SIZE	QTY	SYM	PLATED	TOL
0.2	22	+	YES	+/-0.003
0.25	208	X	YES	+/-0.003
0.9	21	□	YES	+/-0.003
2.42	17	◇	YES	+/-0.13
4.75	4	⧖	NO	+/-0.13
5.21	8	⋈	YES	+/-0.13

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES:
.XX = ± 0.25
XXX = ± 0.127
INTERPRET DIM AND TOL PER ASME Y14.5M-1994
THIRD ANGLE PROJECTION

APPROVALS	
PCB DES.	LT
APP ENG.	SHOUEE L.

SCALE = NONE

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TITLE: FABRICATION DRAWING
20Vin,Dual 5A Step-Down DC/DC µModule® Regulator

SIZE	IC NO.	REV
N/A	LTM4705Y DC3051A	3

FILENAME: DC3051A-3.PCB | SHT 1 OF 1